

PATENT ASSIGNMENT

Electronic Version v1.1

Stylesheet Version v1.1

SUBMISSION TYPE:	NEW ASSIGNMENT												
NATURE OF CONVEYANCE:	ASSIGNMENT												
CONVEYING PARTY DATA													
<table border="1"><thead><tr><th>Name</th><th>Execution Date</th></tr></thead><tbody><tr><td>Byung Tai Do</td><td>03/06/2008</td></tr><tr><td>Seng Guan Chow</td><td>03/06/2008</td></tr><tr><td>Heap Hoe Kuan</td><td>03/06/2008</td></tr><tr><td>Linda Pei Ee Chua</td><td>03/06/2008</td></tr><tr><td>Rui Huang</td><td>03/06/2008</td></tr></tbody></table>	Name	Execution Date	Byung Tai Do	03/06/2008	Seng Guan Chow	03/06/2008	Heap Hoe Kuan	03/06/2008	Linda Pei Ee Chua	03/06/2008	Rui Huang	03/06/2008	
Name	Execution Date												
Byung Tai Do	03/06/2008												
Seng Guan Chow	03/06/2008												
Heap Hoe Kuan	03/06/2008												
Linda Pei Ee Chua	03/06/2008												
Rui Huang	03/06/2008												
RECEIVING PARTY DATA													
<table border="1"><tr><td>Name:</td><td>STATS ChipPAC, Ltd.</td></tr><tr><td>Street Address:</td><td>10 Ang Mo Kio Street 65</td></tr><tr><td>Internal Address:</td><td>#05-17/20 Techpoint</td></tr><tr><td>City:</td><td>Singapore</td></tr><tr><td>State/Country:</td><td>SINGAPORE</td></tr><tr><td>Postal Code:</td><td>569059</td></tr></table>	Name:	STATS ChipPAC, Ltd.	Street Address:	10 Ang Mo Kio Street 65	Internal Address:	#05-17/20 Techpoint	City:	Singapore	State/Country:	SINGAPORE	Postal Code:	569059	
Name:	STATS ChipPAC, Ltd.												
Street Address:	10 Ang Mo Kio Street 65												
Internal Address:	#05-17/20 Techpoint												
City:	Singapore												
State/Country:	SINGAPORE												
Postal Code:	569059												
PROPERTY NUMBERS Total: 1													
<table border="1"><thead><tr><th>Property Type</th><th>Number</th></tr></thead><tbody><tr><td>Application Number:</td><td>12044803</td></tr></tbody></table>	Property Type	Number	Application Number:	12044803									
Property Type	Number												
Application Number:	12044803												
CORRESPONDENCE DATA													
Fax Number: (602)229-5690 <i>Correspondence will be sent via US Mail when the fax attempt is unsuccessful.</i>													
Phone: 602-229-5290													
Email: moneill@quarles.com													
Correspondent Name: Robert D. Atkins													
Address Line 1: QUARLES & BRADY LLP													
Address Line 2: TWO NORTH CENTRAL AVENUE													
Address Line 4: PHOENIX, ARIZONA 85004-2391													
ATTORNEY DOCKET NUMBER:	125155.00092												

CH \$40.00 12044803

500482903

PATENT
REEL: 020623 FRAME: 0696

NAME OF SUBMITTER:

Robert D. Atkins

Total Attachments: 5

source=12044803Assignments#page1.tif

source=12044803Assignments#page2.tif

source=12044803Assignments#page3.tif

source=12044803Assignments#page4.tif

source=12044803Assignments#page5.tif

ASSIGNMENT AND AGREEMENT

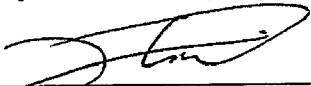
For good and valuable consideration, the receipt of which is hereby acknowledged, I, BYUNG TAI DO of Singapore, have sold, assigned, and transferred, and do hereby sell, as sign, and transfer unto STATS ChipPAC, Ltd. (STATS ChipPAC), a company formed under the laws of the country of Singapore, having its principal office at 10 Ang Mo Kio Street 65, #05-17/20 Techpoint, Singapore 569059, and its successors, assigns, and legal representatives, the entire right, title, and interest in and to certain invention(s) entitled SEMICONDUCTOR PACKAGE HAVING SEMICONDUCTOR DIE WITH INTERNAL VERTICAL INTERCONNECT STRUCTURE AND METHOD THEREFOR, which is described, illustrated, and claimed in any patent application under Attorney Docket No. 125155.00092, together with the entire right, title and interest in and to the application, and in and to any continuation, division, reissue, reexamination, extension, renewal, or substitute thereof, and in and to any patent which may issue upon such application(s).

I hereby sell, assign, and transfer unto STATS ChipPAC, the entire right, title, and interest in and to application(s) for patent filed in all countries foreign to the United States, and in and to application(s) for patent filed under any and all international conventions and treaties, and in and to any patent issuing therefrom, which describe, illustrate, and claim the above -identified invention(s). I hereby also sell, assign, and transfer unto STATS ChipPAC, the entire right, title, and interest in and to all rights under any and all international conventions and treaties in respect of the above -identified invention(s). I authorize STATS ChipPAC to apply for patent in foreign countries directly in its own name, and to claim the priority of the filing date under the provisions of any and all domestic laws and international conventions and treaties.

I hereby authorize and request the government authority in the United States to issue patent(s) upon the aforesaid application, continuation, division, reissue, reexamination, extension, renewal, or substitute, to STATS ChipPAC, for the sole use and behalf of STATS ChipPAC, its successors, assigns, and legal representatives, to the full end of the term for which the patent(s) may be granted, the same as they would have been held and enjoyed by me had this assignment not been made. I authorize and request the equivalent authorities in countries foreign to the United States to issue the patents of their respective countries to and in the name of STATS ChipPAC in the same manner.

I agree that, when requested, I will, without charge to STATS ChipPAC, but at its expense, sign all papers, take all rightful oaths, and do all acts which may be necessary, desirable, or convenient for securing and maintaining patents for the invention(s) in any and all countries and for vesting title thereto in STATS ChipPAC, its successors, assigns, and legal representatives or nominees.

I covenant with STATS ChipPAC, its successors, assigns, and legal representatives that the interest and property hereby conveyed is free from all prior assignment, grant, mortgage, license, or other encumbrance.


Signature for BYUNG TAI DO

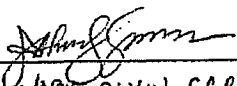
Witnessed on this date:

06 March '08

Signature of Witness:

Printed Name of Witness:

Address of Witness:


JAY ALVIN CAPANAG

BLK 313 #10-474

SEMBANANG DRIVE S780313

QBACTIVE\6094977.1

ASSIGNMENT AND AGREEMENT

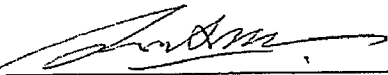
For good and valuable consideration, the receipt of which is hereby acknowledged, I, SENG GUAN CHOW of Singapore, have sold, assigned, and transferred, and do hereby sell, assign, and transfer unto STATS ChipPAC, Ltd. (STATS ChipPAC), a company formed under the laws of the country of Singapore, having its principal office at 10 Ang Mo Kio Street 65, #05-17/20 Techpoint, Singapore 569059, and its successors, assigns, and legal representatives, the entire right, title, and interest in and to certain invention(s) entitled SEMICONDUCTOR PACKAGE HAVING SEMICONDUCTOR DIE WITH INTERNAL VERTICAL INTERCONNECT STRUCTURE AND METHOD THEREFOR, which is described, illustrated, and claimed in any patent application under Attorney Docket No. 125155.00092, together with the entire right, title and interest in and to the application, and in and to any continuation, division, reissue, reexamination, extension, renewal, or substitute thereof, and in and to any patent which may issue upon such application(s).

I hereby sell, assign, and transfer unto STATS ChipPAC, the entire right, title, and interest in and to application(s) for patent filed in all countries foreign to the United States, and in and to application(s) for patent filed under any and all international conventions and treaties, and in and to any patent issuing therefrom, which describe, illustrate, and claim the above -identified invention(s). I hereby also sell, assign, and transfer unto STATS ChipPAC, the entire right, title, and interest in and to all rights under any and all international conventions and treaties in respect of the above -identified invention(s). I authorize STATS ChipPAC to apply for patent in foreign countries directly in its own name, and to claim the priority of the filing date under the provisions of any and all domestic laws and international conventions and treaties.

I hereby authorize and request the government authority in the United States to issue patent(s) upon the aforesaid application, continuation, division, reissue, reexamination, extension, renewal, or substitute, to STATS ChipPAC, for the sole use and behalf of STATS ChipPAC, its successors, assigns, and legal representatives, to the full end of the term for which the patent(s) may be granted, the same as they would have been held and enjoyed by me had this assignment not been made. I authorize and request the equivalent authorities in countries foreign to the United States to issue the patents of their respective countries to and in the name of STATS ChipPAC in the same manner.

I agree that, when requested, I will, without charge to STATS ChipPAC, but at its expense, sign all papers, take all rightful oaths, and do all acts which may be necessary, desirable, or convenient for securing and maintaining patents for the invention(s) in any and all countries and for vesting title thereto in STATS ChipPAC, its successors, assigns, and legal representatives or nominees.

I covenant with STATS ChipPAC, its successors, assigns, and legal representatives that the interest and property hereby conveyed is free from all prior assignment, grant, mortgage, license, or other encumbrance.



Signature for SENG GUAN CHOW

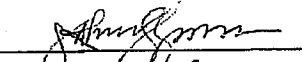
Witnessed on this date:

06 March 08

Signature of Witness:

Printed Name of Witness:

Address of Witness:


JOSE AWIS CAPARAS
BLK 313 #10-474
SEMPANANG DRIVE 575713

QBACTIVE\6095376.1

ASSIGNMENT AND AGREEMENT

For good and valuable consideration, the receipt of which is hereby acknowledged, I, HEAP HOE KUAN of Singapore, have sold, assigned, and transferred, and do hereby sell, assign, and transfer unto STATS ChipPAC, Ltd. (STATS ChipPAC), a company formed under the laws of the country of Singapore, having its principal office at 10 Ang Mo Kio Street 65, #05-17/20 Techpoint, Singapore 569059, and its successors, assigns, and legal representatives, the entire right, title, and interest in and to certain invention(s) entitled SEMICONDUCTOR PACKAGE HAVING SEMICONDUCTOR DIE WITH INTERNAL VERTICAL INTERCONNECT STRUCTURE AND METHOD THEREFOR, which is described, illustrated, and claimed in any patent application under Attorney Docket No. 125155.00092, together with the entire right, title and interest in and to the application, and in and to any continuation, division, reissue, reexamination, extension, renewal, or substitute thereof, and in and to any patent which may issue upon such application(s).

I hereby sell, assign, and transfer unto STATS ChipPAC, the entire right, title, and interest in and to application(s) for patent filed in all countries foreign to the United States, and in and to application(s) for patent filed under any and all international conventions and treaties, and in and to any patent issuing therefrom, which describe, illustrate, and claim the above -identified invention(s). I hereby also sell, assign, and transfer unto STATS ChipPAC, the entire right, title, and interest in and to all rights under any and all international conventions and treaties in respect of the above -identified invention(s). I authorize STATS ChipPAC to apply for patent in foreign countries directly in its own name, and to claim the priority of the filing date under the provisions of any and all domestic laws and international conventions and treaties.

I hereby authorize and request the government authority in the United States to issue patent(s) upon the aforesaid application, continuation, division, reissue, reexamination, extension, renewal, or substitute, to STATS ChipPAC, for the sole use and behalf of STATS ChipPAC, its successors, assigns, and legal representatives, to the full end of the term for which the patent(s) may be granted, the same as they would have been held and enjoyed by me had this assignment not been made. I authorize and request the equivalent authorities in countries foreign to the United States to issue the patents of their respective countries to and in the name of STATS ChipPAC in the same manner.

I agree that, when requested, I will, without charge to STATS ChipPAC, but at its expense, sign all papers, take all rightful oaths, and do all acts which may be necessary, desirable, or convenient for securing and maintaining patents for the invention(s) in any and all countries and for vesting title thereto in STATS ChipPAC, its successors, assigns, and legal representatives or nominees.

I covenant with STATS ChipPAC, its successors, assigns, and legal representatives that the interest and property hereby conveyed is free from all prior assignment, grant, mortgage, license, or other encumbrance.

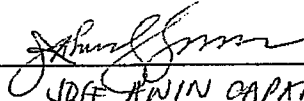


Signature for HEAP HOE KUAN

Witnessed on this date:

06 March '08

Signature of Witness:



Printed Name of Witness:

JOSE ANWIN OAPAMS

Address of Witness:

BLK 313 #10-474

SEMPANG DRIVE 570313

QBACTIVE\6095377.1

ASSIGNMENT AND AGREEMENT

For good and valuable consideration, the receipt of which is hereby acknowledged, I, LINDA PEI EE CHUA of Singapore, have sold, assigned, and transferred, and do hereby sell, assign, and transfer unto STATS ChipPAC, Ltd. (STATS ChipPAC), a company formed under the laws of the country of Singapore, having its principal office at 10 Ang Mo Kio Street 65, #05-17/20 Techpoint, Singapore 569059, and its successors, assigns, and legal representatives, the entire right, title, and interest in and to certain invention(s) entitled SEMICONDUCTOR PACKAGE HAVING SEMICONDUCTOR DIE WITH INTERNAL VERTICAL INTERCONNECT STRUCTURE AND METHOD THEREFOR, which is described, illustrated, and claimed in any patent application under Attorney Docket No. 125155.00092, together with the entire right, title and interest in and to the application, and in and to any continuation, division, reissue, reexamination, extension, renewal, or substitute thereof, and in and to any patent which may issue upon such application(s).

I hereby sell, assign, and transfer unto STATS ChipPAC, the entire right, title, and interest in and to application(s) for patent filed in all countries foreign to the United States, and in and to application(s) for patent filed under any and all international conventions and treaties, and in and to any patent issuing therefrom, which describe, illustrate, and claim the above -identified invention(s). I hereby also sell, assign, and transfer unto STATS ChipPAC, the entire right, title, and interest in and to all rights under any and all international conventions and treaties in respect of the above -identified invention(s). I authorize STATS ChipPAC to apply for patent in foreign countries directly in its own name, and to claim the priority of the filing date under the provisions of any and all domestic laws and international conventions and treaties.

I hereby authorize and request the government authority in the United States to issue patent(s) upon the aforesaid application, continuation, division, reissue, reexamination, extension, renewal, or substitute, to STATS ChipPAC, for the sole use and behalf of STATS ChipPAC, its successors, assigns, and legal representatives, to the full end of the term for which the patent(s) may be granted, the same as they would have been held and enjoyed by me had this assignment not been made. I authorize and request the equivalent authorities in countries foreign to the United States to issue the patents of their respective countries to and in the name of STATS ChipPAC in the same manner.

I agree that, when requested, I will, without charge to STATS ChipPAC, but at its expense, sign all papers, take all rightful oaths, and do all acts which may be necessary, desirable, or convenient for securing and maintaining patents for the invention(s) in any and all countries and for vesting title thereto in STATS ChipPAC, its successors, assigns, and legal representatives or nominees.

I covenant with STATS ChipPAC, its successors, assigns, and legal representatives that the interest and property hereby conveyed is free from all prior assignment, grant, mortgage, license, or other encumbrance.



Signature for LINDA PEI EE CHUA

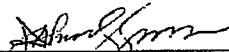
Witnessed on this date:

02 March '18

Signature of Witness:

Printed Name of Witness:

Address of Witness:


JUSE ANWIN CAPANG
BLK 713 #10-474
SEMBAWANG DRIVE S70213

QBACTIVE\6095378.1

ASSIGNMENT AND AGREEMENT

For good and valuable consideration, the receipt of which is hereby acknowledged, I, RUI HUANG of Singapore, have sold, assigned, and transferred, and do hereby sell, assign, and transfer unto STATS ChipPAC, Ltd. (STATS ChipPAC), a company formed under the laws of the country of Singapore, having its principal office at 10 Ang Mo Kio Street 65, #05-17/20 Techpoint, Singapore 569059, and its successors, assigns, and legal representatives, the entire right, title, and interest in and to certain invention(s) entitled SEMICONDUCTOR PACKAGE HAVING SEMICONDUCTOR DIE WITH INTERNAL VERTICAL INTERCONNECT STRUCTURE AND METHOD THEREFOR, which is described, illustrated, and claimed in any patent application under Attorney Docket No. 125155.00092, together with the entire right, title and interest in and to the application, and in and to any continuation, division, reissue, reexamination, extension, renewal, or substitute thereof, and in and to any patent which may issue upon such application(s).

I hereby sell, assign, and transfer unto STATS ChipPAC, the entire right, title, and interest in and to application(s) for patent filed in all countries foreign to the United States, and in and to application(s) for patent filed under any and all international conventions and treaties, and in and to any patent issuing therefrom, which describe, illustrate, and claim the above -identified invention(s). I hereby also sell, assign, and transfer unto STATS ChipPAC, the entire right, title, and interest in and to all rights under any and all international conventions and treaties in respect of the above -identified invention(s). I authorize STATS ChipPAC to apply for patent in foreign countries directly in its own name, and to claim the priority of the filing date under the provisions of any and all domestic laws and international conventions and treaties.

I hereby authorize and request the government authority in the United States to issue patent(s) upon the aforesaid application, continuation, division, reissue, reexamination, extension, renewal, or substitute, to STATS ChipPAC, for the sole use and behalf of STATS ChipPAC, its successors, assigns, and legal representatives, to the full end of the term for which the patent(s) may be granted, the same as they would have been held and enjoyed by me had this assignment not been made. I authorize and request the equivalent authorities in countries foreign to the United States to issue the patents of their respective countries to and in the name of STATS ChipPAC in the same manner.

I agree that, when requested, I will, without charge to STATS ChipPAC, but at its expense, sign all papers, take all rightful oaths, and do all acts which may be necessary, desirable, or convenient for securing and maintaining patents for the invention(s) in any and all countries and for vesting title thereto in STATS ChipPAC, its successors, assigns, and legal representatives or nominees.

I covenant with STATS ChipPAC, its successors, assigns, and legal representatives that the interest and property hereby conveyed is free from all prior assignment, grant, mortgage, license, or other encumbrance.

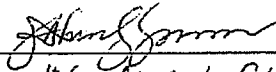


Signature for RUI HUANG

Witnessed on this date:

06 March '08

Signature of Witness:



Printed Name of Witness:

JOSE ANWAR CAPARAS

Address of Witness:

BLK 313 #10-474

SEMBAWANG DR. S77313

QBACTIVE\6095375.1